



Specification of Automotive MLCC

• Supplier : Samsung electro-mechanics • Samsung P/N : CL21C221JB61PNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 220 pF, 50V, ±5%, C0G, 0805

AEC-Q 200 Specified

A. Samsung Part Number

<u>CL</u> <u>21</u> <u>C</u> <u>221</u> <u>J</u> <u>B</u> <u>6</u> <u>1</u> <u>P</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor					
2	Size	0805 (inch code)	L: 2.0 ± 0	.1 mm	W:	1.25 ± 0.1	mm
3	Dielectric	C0G	8 Inn	er electrode	Ni		
4	Capacitance	220 pF	Ter	rmination	Cu		
⑤	Capacitance	±5 %	Pla	iting	Sn	100%	(Pb Free)
	tolerance		9 Pro	oduct	Aut	tomotive	
6	Rated Voltage	50 V	⑩ Gra	ade code	Sta	andard	
7	Thickness	0.6 ± 0.1 mm	① Pac	ckaging	Ca	rdboard Typ	e, 7" reel

B. Reliablility Test and Judgement condition

	Performance	Test condition			
High Temperature	Appearance : No abnormal exterior appearance	Unpowered, 1000hrs@T=150 ℃			
Exposure	Capacitance Change :	Measurement at 24±2hrs after test conclusion			
	within ±2.5% or ±0.25pF whichever is larger				
	Q: 1000 min				
	IR : More than 10,000№ or 500№×μF				
	Whichever is Smaller				
Temperature Cycling	Appearance : No abnormal exterior appearance	1000Cycles			
	Capacitance Change :	Measurement at 24±2hrs after test conclusion			
	within ±2.5% or ±0.25pF whichever is larger	1 cycle condition :			
	Q: 1000 min	-55+0/-3 °C (15±3min) -> Room Temp(1min.)			
	IR : More than 10,000 № or 500 № μF	-> 125+3/-0 ℃ (15±3min) -> Room Temp(1min.)			
	Whichever is Smaller				
Destructive Physical	No Defects or abnormalities	Per EIA 469			
Analysis					
Moisture Resistance	Appearance : No abnormal exterior appearance	10Cycles, t=24hrs/cycle			
	Capacitance Change :	Heat (25~65 °C) and humidity (80~98%), Unpowered			
	within ±2.5% or ±0.25pF whichever is larger	measurement at 24±2hrs after test conclusion			
	Q: 350 min				
	IR : More than 10,000MΩ or 500MΩ×μF				
	Whichever is Smaller				
Humidity Bias	Appearance : No abnormal exterior appearance	1000hrs 85 °C/85%RH, Rated Voltate and 1.3~1.5V,			
	Capacitance Change :	Add 100kohm resistor			
	within ±2.5% or ±0.25pF whichever is larger	Measurement at 24±2hrs after test conclusion			
	Q: 200 min	The charge/discharge current is less than 50mA.			
	IR : More than 500 MΩ or 25 MΩ×μF				
	Whichever is Smaller				
High Temperature	Appearance : No abnormal exterior appearance	1000hrs @ TA=125 ℃, 200% Rated Voltage,			
Operating Life	Capacitance Change :	Measurement at 24±2hrs after test conclusion			
	within ±3.0% or ±0.3pF whichever is larger	The charge/discharge current is less than 50mA.			
	Q: 350 min				
	IR : More than 10,000№ or 500№×μF				
	Whichever is Smaller				

	Performance	Test condition		
External Visual	No abnormal exterior appearance	Microscope (´10)		
Physical Dimensions	Within the specified dimensions	Using The calipers		
Mechanical Shock	Appearance : No abnormal exterior appearance	Three shocks in each direction should be applied along		
	Capacitance Change :	3 mutually perpendicular axes of the test specimen (18 shocks)		
	within ±2.5% or ±0.25pF whichever is larger	Peakvalue Duration Wave Velocity		
	Q, IR: initial spec.	1,500G 0.5ms Half sine 4.7m/sec.		
Vibration	Appearance : No abnormal exterior appearance	5g's for 20min., 12cycles each of 3 orientations,		
	Capacitance Change :	Use 8"x5" PCB 0.031" Thick 7 secure points on one long side		
	within ±2.5% or ±0.25pF whichever is larger	and 2 secure points at corners of opposite sides. Parts mounted		
	Q, IR : initial spec.	within 2" from any secure point. Test from 10~2000 Hz.		
Resistance to	Appearance : No abnormal exterior appearance	Solder pot : 260±5 °C, 10±1sec.		
Solder Heat	Capacitance Change :			
	within ±2.5% or ±0.25pF whichever is larger			
	Q, IR : initial spec.			
Thermal Shock	Appearance : No abnormal exterior appearance	-55 ℃/+125 ℃.		
	Capacitance Change :	Note: Number of cycles required-300,		
	within ±2.5% or ±0.25pF whichever is larger	Maximum transfer time-20 sec, Dwell time-15min. Air-Air		
	Q, IR: initial spec.			
ESD	Appearance : No abnormal exterior appearance	AEC-Q200-002		
	Capacitance Change :			
	within ±2.5% or ±0.25pF whichever is larger			
	Q, IR: initial spec.			
Solderability	95% of the terminations is to be soldered	a) Preheat at 155 °C for 4 hours, Immerse in solder for 5s at 245±5 °C		
	evenly and continuously	b) Steam aging for 8 hours, Immerse in solder for 5s at 245±5 °C		
		c) Steam aging for 8 hours, Immerse in solder for 120s at 260±5 °C		
Flootoical	One of the control of	solder : a solution ethanol and rosin		
Electrical	Capacitance: Within specified tolerance	The Capacitance /Q should be measured at 25 °C,		
Characterization	Q: 1000 max.	1Mb±10%, 0.5~5Vrms		
	IR(25 °C): More than 100,000 № or 1,000 № ×μF	I.R. should be measured with a DC voltage not exceeding		
	IR(125°C): More than10,000 № or 100 № × µF Whichever is Smaller	Rated Voltage @25°C, @125°C for 60~120 sec.		
		Dielectric Strength: 250% of the rated voltage for 1~5 seconds		
Board Flex	Dielectric Strength Appearance : No abnormal exterior appearance	Bending to the limit (3mm) for 5 seconds		
Board Flex	Capacitance Change:	behaling to the littlit (Sillil) for 3 seconds		
	l '			
Terminal	within ±5.0% or ±0.5pF whichever is larger Appearance: No abnormal exterior appearance	18N, for 60±1 sec.		
Strength(SMD)	Capacitance Change:	101, 101 0021 000.		
on onguitonib)	within ±2.5% or ±0.25pF whichever is larger			
Beam Load	Destruction value should not be exceed	Beam speed		
	Chip Length < 2.5mm	0.5±0.05mm/sec		
	a) Chip Thickness > 0.5mm : 20N			
	b) Chip Thickness > 0.5mm : 8N			
Temperature	COG			
Characterisitcs	(From -55 ℃ to 125 ℃, Capacitance change shoud	be within +30PPM/°C)		
Character Isites	(1. 15.11 55 5 to 125 5, Capacitatice change should	00 WIGHT ±001 1 W/ 0)		

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}\!\!\!\mathrm{C}$, 10sec. Max)

Meet IPC/JEDEC J-STD-020 D Standard

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.